

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Dongming HUO</td> <td>06/09/2012</td> </tr> <tr> <td>Hongpo HU</td> <td>06/09/2012</td> </tr> <tr> <td>Chunlin XIE</td> <td>06/06/2012</td> </tr> <tr> <td>Wang ZHANG</td> <td>06/06/2012</td> </tr> </tbody> </table>		Name	Execution Date	Dongming HUO	06/09/2012	Hongpo HU	06/09/2012	Chunlin XIE	06/06/2012	Wang ZHANG	06/06/2012		
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RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>SHENZHEN BYD AUTO R&D COMPANY LIMITED</td> </tr> <tr> <td>Street Address:</td> <td>Part B, 1/F, BLDG #B2, Yucan Industrial Area, Lanzhu Road</td> </tr> <tr> <td>Internal Address:</td> <td>Shenzhen Export Processing Zone, Shenzhen Grand Industrial Zone</td> </tr> <tr> <td>City:</td> <td>Shenzhen, Guangdong, P.R.</td> </tr> <tr> <td>State/Country:</td> <td>CHINA</td> </tr> <tr> <td>Postal Code:</td> <td>518118</td> </tr> </table>		Name:	SHENZHEN BYD AUTO R&D COMPANY LIMITED	Street Address:	Part B, 1/F, BLDG #B2, Yucan Industrial Area, Lanzhu Road	Internal Address:	Shenzhen Export Processing Zone, Shenzhen Grand Industrial Zone	City:	Shenzhen, Guangdong, P.R.	State/Country:	CHINA	Postal Code:	518118
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number:	(202)408-4400												
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Email:	faxserve@finnegan.com												
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.													

OP \$40.00 13536784

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ATTORNEY DOCKET NUMBER:	11245.0061
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NAME OF SUBMITTER:	R. CREMEANS
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Total Attachments: 6 source=ASSIGNMENT#page1.tif source=ASSIGNMENT#page2.tif source=ASSIGNMENT#page3.tif source=ASSIGNMENT#page4.tif source=ASSIGNMENT#page5.tif source=ASSIGNMENT#page6.tif
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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), (hereinafter referred to as Assignor(s)), have made an invention entitled:

EPITAXIAL WAFER FOR LIGHT EMITTING DIODE, LIGHT EMITTING DIODE CHIP AND METHODS FOR MANUFACTURING THE SAME
for which I/WE executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on [Date], 20[Year] (Application No. [Text]); and

WHEREAS, Shenzhen BYD Auto R&D Company Limited
a corporation of China

whose post office address is PART B, 1/F, BLDG#B2, YUCAN INDUSTRIAL AREA, Lanzhu Road, Shenzhen Export Processing Zone, Shenzhen Grand Industrial Zone, Shenzhen, Guangdong, 518118 P.R.China

and BYD COMPANY LIMITED
a corporation of China

whose post office address is No.3009, BYD Road, Pingshan, Shenzhen, Guangdong, 518118, P.R.China
(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;


AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No.[Text], filed [Date]) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

1. FULL NAME OF SOLE OR FIRST ASSIGNOR Dongming HUO	ASSIGNOR'S SIGNATURE	DATE
ADDRESS No.3009, BYD Road, Pingshan, Shenzhen, Guangdong, 518118, P.R.China		CITIZENSHIP Shenzhen, China
2. FULL NAME OF SECOND ASSIGNOR, IF ANY Hongpo HU;	ASSIGNOR'S SIGNATURE	DATE
ADDRESS No.3009, BYD Road, Pingshan, Shenzhen, Guangdong, 518118, P.R.China		CITIZENSHIP Shenzhen, China
3. FULL NAME OF THIRD ASSIGNOR, IF ANY Chunlin XIE;	ASSIGNOR'S SIGNATURE 谢春林	DATE 2012.6.6
ADDRESS No.3009, BYD Road, Pingshan, Shenzhen, Guangdong, 518118, P.R.China		CITIZENSHIP Shenzhen, China

SOLE/JOINT INVENTION
(U.S. Rights Only)
Attorney Docket No. 11245.0061-00000

4. FULL NAME OF FOURTH ASSIGNOR, IF ANY Wang ZHANG	ASSIGNOR'S SIGNATURE 	DATE 2-12-06
ADDRESS No.3009, BYD Road, Pingshan, Shenzhen, Guangdong, 518118, P.R.China		CITIZENSHIP Shenzhen, China

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AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

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